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Application Number 10/712,229

Filing Date Nov. 12, 2003

First Named Inventor Van Brocklin et al.

Art Unit 2871 2677

Examiner Name Net assigned P. D.H. Appliff

Attorney Docket Number 200309795-1

Examiner	Cite No.1	Document Number	Publication Date	Name of Patentee or	Pages, Columns, Lines, Where Relevant Passages or Relevant
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Date Considered 06-21-66

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		European Search Report dated March 23, 2005.	
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^{*}EXAMINER: Initial/irreference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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